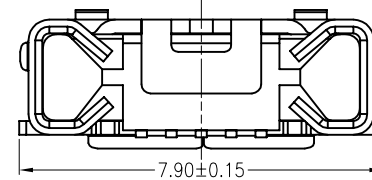
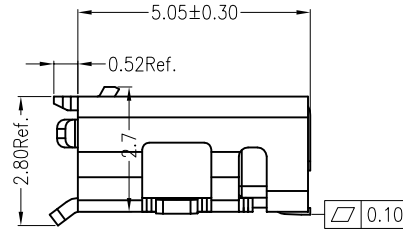
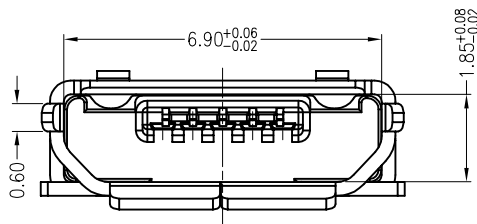
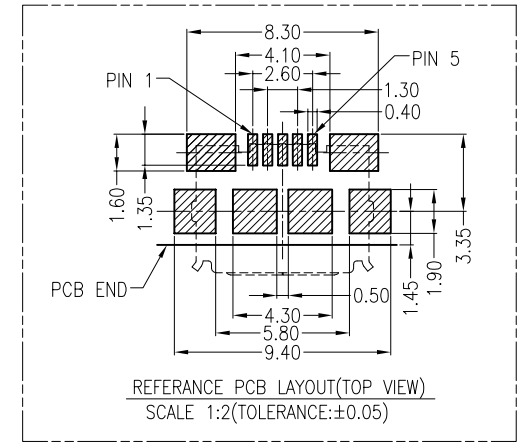
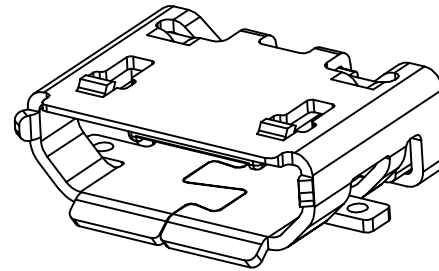
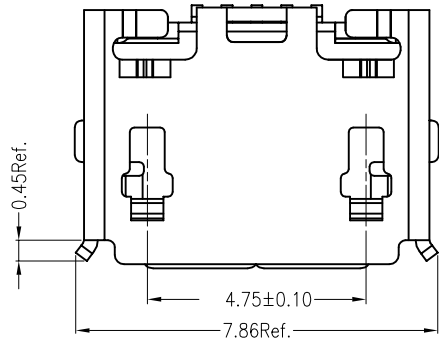


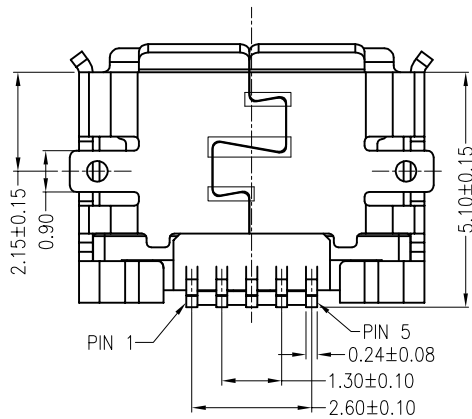
THE PART MEETS TECONN "GP001" COMPLIANCE



A4A0502-B-XX-R

Mating Area plating

- 01: Au 1u"Min.
- 03: Au 3u"Min.
- 05: Au 5u"Min.
- 10: Au 10u"Min.
- 15: Au 15u"Min.
- 30: Au 30u"Min.



- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose
1	Shell	Stainless Steel	Matte Tin 80u"min.
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:Gold2u"min.
3	InsertMolding	LCP	UL94V-0

X. ± 0.35	APPD:	TITLE:	MICRO USB B/F 5PIN SMT	
.X ± 0.25	CHKD:			
.XXX±				
X* ± 2°	DR:	Kevin Han	PART NO:	A4A0502-B-XX-R
.X* ± 1.5°			DWG NO:	C-A4A0502-B-XX-R
		UNITS:	SCALE:	CUSTOMER DRAWING
		mm	1:1	SHEET:1OF1
				REV: A

A	TE2011-0016	New Drawing	2011/04/25
REV	ECN NO	DESCRIPTION	DATE